CLAIMS

1. A manufacturing apparatus for medical tablets, which manufactures an IC chip member-containing tablet by supplying an IC chip member equipped with an IC on pharmaceutical powder filled in a die hole, thereafter filling pharmaceutical powder onto the IC chip member, and compressing these pharmaceutical powder and the IC chip member from above and below, wherein

the IC chip member has a base plane, and a convex portion protruding more on one side than the other side with respect to the base plane, and

said manufacturing apparatus for medical tablets comprises a supply portion which holds the IC chip member in a downward manner where the convex portion faces downward, and supplies the IC chip member on the pharmaceutical powder.

2. The manufacturing apparatus for medical tablets according to claim 1, wherein

the IC chip member is set in an accommodation portion provided in a carrier tape, in an upward manner where the convex portion faces upward, and is accommodated in an accommodation tape in which an opening side of the accommodation portion is covered with a top tape, and

the IC chip member in said upward manner is taken out of said accommodation portion, the taken-out IC chip member is reversed upside down and changed to said downward manner, and thereafter the supply portion supplies the IC chip member.

3. A manufacturing apparatus for medical tablets, which manufactures an IC chip member-containing tablet by supplying an IC chip member equipped with an IC on pharmaceutical powder filled in a die hole, thereafter filling pharmaceutical powder onto the IC chip member, and compressing these pharmaceutical powder and the IC chip member from above and below, comprising:

a first suction member which suctions and holds the IC chip member;

a second suction member which suctions the IC chip member held by said first suction member, from a side opposite to said first suction member; and

a guide member provided with a through-hole into which the IC chip member is to be inserted, wherein

a suction portion of said first suction member is inserted from one side of said through-hole, and a suction portion of said second suction member is inserted from the other side of said through-hole, and

the IC chip member is passed from said first suction member to said second suction member within said through-hole.

4. The manufacturing apparatus for medical tablets according to claim 3, wherein

inner shape dimensions of said through-hole are formed to be wide at end portions on said one side and the other side, and to be narrow at an intermediate position, and

the IC chip member is passed at said intermediate position.

5. The manufacturing apparatus for medical tablets according to claim 3, wherein

the IC chip member is accommodated in a carrier tape, and

said first suction member suctions and holds the IC chip member within the carrier tape, rotates by a set angle, and inserts the IC chip member into said through-hole in said guide member.

6. The manufacturing apparatus for medical tablets according to claim 3, wherein

said guide member includes a plurality of moving guide members, and a drive mechanism which causes the plurality of moving guide members to come close to or

separate from each other, and

the plurality of moving guide members come close to each other to form said through-hole.

7. A manufacturing apparatus for medical tablets, which manufactures an IC chip member-containing tablet by supplying an IC chip member on pharmaceutical powder filled in a die hole, further filling pharmaceutical powder onto the IC chip member, and compressing these pharmaceutical powder and the IC chip member from above and below, comprising:

a positioning guide which has a through-hole penetrating up and down, and holds the IC chip member within the through-hole; and

a push-out portion arranged above the positioning guide for pushing out said IC chip member downward, wherein

a plurality of protrusions protruding toward a center are provided on an inside of said through-hole, and said IC chip member is held by the protrusions.

8. The manufacturing apparatus for medical tablets according to claim 7, wherein said plurality of protrusions are convex threads extending along an axial direction of said through-hole.

9. The manufacturing apparatus for medical tablets according to claim 8, wherein said convex threads are formed to a lower end of said through-hole.

10. The manufacturing apparatus for medical tablets according to claim 8, wherein

said positioning guide is provided to a rotation member, and

the IC chip member is pushed from above into said positioning guide located at a receiving position and the IC chip member is held by said protrusions, and, in a state where said positioning guide holding the IC chip member rotates and moves together

with rotation of said rotation member and is located above said die hole of a tabletting machine, the held IC chip member is supplied into said die hole by said push-out portion.

11. A manufacturing method for medical tablets, comprising the steps of:

holding an IC chip member, which has a base plane and a convex portion protruding more on one side than on the other side with respect to the base plane, in a downward manner where the convex portion faces downward, and supplying the IC chip member in the downward manner on pharmaceutical powder filled in a die hole; and

manufacturing a tablet containing said IC chip by filling pharmaceutical powder onto said IC chip member, and compressing these pharmaceutical powder and said IC chip member from above and below.

12. A manufacturing method for medical tablets, comprising the steps of:

a first suction member suctioning and holding an IC chip member;

inserting a suction portion of said first suction member from one side of a through-hole, inserting a suction portion of a second suction member from the other side of said through-hole, passing said IC chip member from said suction member to said second suction member within said through-hole to hold said IC chip member, and thereafter supplying said IC chip member on pharmaceutical powder filled in a die hole; and

manufacturing a tablet containing said IC chip member by filling pharmaceutical powder onto said IC chip member, and compressing these pharmaceutical powder and said IC chip member from above and below.

13. A manufacturing method for medical tablets, comprising the steps of:

holding an IC chip member with a plurality of protrusions protruding toward a center provided on an inside of a through-hole in a positioning guide;

supplying said IC chip member held within said through-hole on pharmaceutical powder filled in a die hole; and

manufacturing a tablet containing said IC chip member by filling pharmaceutical powder onto said IC chip member, and compressing these pharmaceutical powders and said IC chip member from above and below.

14. The manufacturing method for medical tablets according to claim 13, further comprising the step of pushing said IC chip member from above into said positioning guide located at a receiving position, wherein

the step of supplying said IC chip member includes supplying said held IC chip member into said die hole by a push-out portion, in a state where said positioning guide holding said IC chip member moves rotationally together with rotation of a rotation member and is located above said die hole of a tabletting machine.

15. A medical tablet including an IC chip member equipped with an IC therein, said medical tablet having a first surface and a second surface spaced from each other in an up/down direction, wherein

an engraved stamp or cleavage line is formed in said first surface,

an engraved stamp or cleavage line is not formed or an engraved stamp or cleavage line shallower than that in said first surface is formed in said second surface, and

said IC chip member has a base plane and a convex portion protruding more on one side than on the other side with respect to said base plane, and the convex portion is arranged within the medical tablet to face the second face.